

A¹ circuit patterns being provided in the cable section, and covered by a soft laminated adhesive, the adhesive being the outermost layers of the cable section.

A² 3. (Amended) The flexible printed circuit board as described in Claim 1, the laminated adhesive comprising a polyimide adhesive.

A³ 5. (Amended) A method for manufacturing a flexible printed circuit board having a component mount section, which comprises an outer-layer material laminated on an inner-layer material with an insulating cover therebetween, and a cable section, which comprises the inner-layer material covered by the insulating cover and connects to the component mount section, the method comprising the step of:
covering the inner-layer material of the component mount section and the cable section with a soft laminated adhesive, the soft laminated adhesive being the outermost layer of the cable section.

Please add the following new claims:

A⁴ 6. (New) A flexible printed circuit board having a cable section connected to at least one component mount section comprising:
a circuit strata comprising at least one circuit layer, the circuit strata comprising all the circuit layers of the circuit board, wherein the circuit strata is located in both the cable section and in at least one of the at least one component mount section, the strata of the cable section connecting to the strata of the at least one of the least one component mount section; wherein
at least one circuit pattern is provided in at least one of the circuit layers in the cable section of the circuit strata, wherein
at least one of the top and bottom of the circuit strata is covered by a soft laminated adhesive, and wherein
the printed circuit board is adapted at the at least one mount section to permit an electronic component to be mounted on the component mount section.

7. (New) The board of claim 6, wherein the soft laminated adhesive is an outermost layer of the top and bottom of the cable section.

8. (New) The board of claim 6, wherein the soft laminated adhesive comprises polyimide.
9. (New) The board of claim 6, wherein the soft laminated adhesive comprises acrylic.
10. (New) The board of claim 6, wherein the soft laminated adhesive is in substantial contact with the circuit strata.
11. (New) The board of claim 6, wherein the soft laminated adhesive is in substantial contact with a circuit layer.
12. (New) The board of claim 6, wherein both the top and the bottom of the circuit strata is covered by a soft laminated adhesive.

A4
cont.

13. (New) A flexible printed circuit board having a cable section connected to at least one component mount section comprising:

a circuit strata comprising at least one circuit layer, the circuit strata comprising all the circuit layers of the circuit board, wherein the circuit strata is located in both the cable section and in at least one of the at least one component mount section, the strata of the cable section connecting to the strata of the at least one of the least one component mount section; wherein

at least one circuit pattern is provided in at least one of the circuit layers in the cable section of the circuit strata, wherein

at least one of the top and bottom of the circuit strata is covered by a soft laminated adhesive, the soft laminated adhesive being an outermost layer of the cable section, and wherein

the printed circuit board is adapted at the at least one mount section to permit an electronic component to be mounted on the component mount section.

14. (New) The board of claim 13, wherein the soft laminated adhesive is in contact with the circuit strata.

15. (New) The board of claim 13, wherein both the top and the bottom of the circuit strata is covered by a soft laminated adhesive, the soft laminated adhesive being the outermost layers of the cable section.

16. (New) A flexible printed circuit board having a cable section connected to at least one component mount section comprising:

a circuit strata comprising at least one circuit layer, the circuit strata comprising all the circuit layers of the circuit board, wherein the circuit strata is located in both the cable section and in at least one of the at least one component mount section, the strata of the cable section connecting to the strata of the at least one of the least one component mount section; wherein

at least one circuit pattern is provided in at least one of the circuit layers in the cable section of the circuit strata, and wherein

at least one of the top and bottom of the circuit strata of the cable section is covered only by an adhesive.

17 (New) The board of claim 16, wherein the soft laminated adhesive comprises polyimide.

18. (New) The board of claim 16, wherein the soft laminated adhesive comprises acrylic.

19. (New) The board of claim 16, wherein the soft laminated adhesive is in contact with the circuit strata.

20. (New) The board of claim 16, wherein both the top and bottom of the circuit strata of the cable section is covered only by an adhesive.

21. (New) A flexible printed circuit board comprising at least one cover layer, the at least one cover layer being located at the outermost portion of at least one side of the board, wherein at least one of the at least one cover layer is an adhesive and not a cover film.

A4

22. (New) The board of claim 21, wherein the board comprises a cover layer on both sides of the board.

IN THE SPECIFICATION:

On page 3, please replace the paragraph spanning lines 9-16 with the following:

A5

Since the laminating adhesive 3 is the outermost layer of the cable section, it is preferable that the material used for the laminating adhesive 3 should be properly hard and soft enough to function as a cable section while capable of maintaining an average thickness. Materials, which satisfy these conditions, include polyimide and acrylic adhesives. A thin film of such material can be provided evenly over the surface of the inner-layer material 1.
